

IN THE CLAIMS

Please substitute claims 1-17 with the following:

1. (Currently Amended) A solid-state image pickup device comprising:
a circuit board having an opening;
a sensor package in which a chip of a solid-state image pickup element with a light-receiving surface is placed, the sensor package disposed at one surface of the circuit board so that the light-receiving surface of the chip of the solid-state image pickup element opposes the opening of the circuit board;
a seal adhered to the sensor package for sealing in the solid-state image pickup element;
and
an optical unit disposed at the other surface of the circuit board so that incident light is focused on the light-receiving surface[[.]];
wherein₁
the circuit board is disposed between the sensor package and the optical unit, ~~and~~
the circuit board has substantially flat surfaces,
the solid-state image pickup element is disposed on a surface of the sensor package, and
~~wherein~~ the seal is placed within the opening of the circuit board.
2. (Original) A solid-state image pickup device according to Claim 1, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.
3. (Original) A solid-state image pickup device according to Claim 1, wherein the solid-state image pickup element has a signal processing function.

4. (Original) A solid-state image pickup device according to Claim 1, wherein the circuit board is connected to an external device without a connector.

5. (Currently Amended) A method of producing a solid-state image pickup device comprising the steps of:

providing a circuit board with an opening;

joining a sensor package, in which a chip of a solid-state image pickup element has been previously sealed, to one surface of the circuit board so that a light-receiving surface of the chip of the solid-state image pickup element opposes the opening of the circuit board; and

disposing and joining an optical unit at and to the other surface of the circuit board so that incident light is focused on the light-receiving surface,

wherein,

the circuit board is disposed between the sensor package and the optical unit,

the circuit board has substantially flat surfaces, and

the solid-state image pickup element is disposed on a surface of the sensor package.

6. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.

7. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the solid-state image pickup element has a signal processing function.

8. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the circuit board is connected to an external device without a connector.

9. (Previously Presented) A solid-state image pickup device according to Claim 1, wherein the seal is a glass seal.

10. (Previously Presented) A method of producing a solid-state image pickup device according to Claim 5, further comprising placing a seal adhered to the sensor package within the opening of the circuit board.

11-17. (Cancelled).